



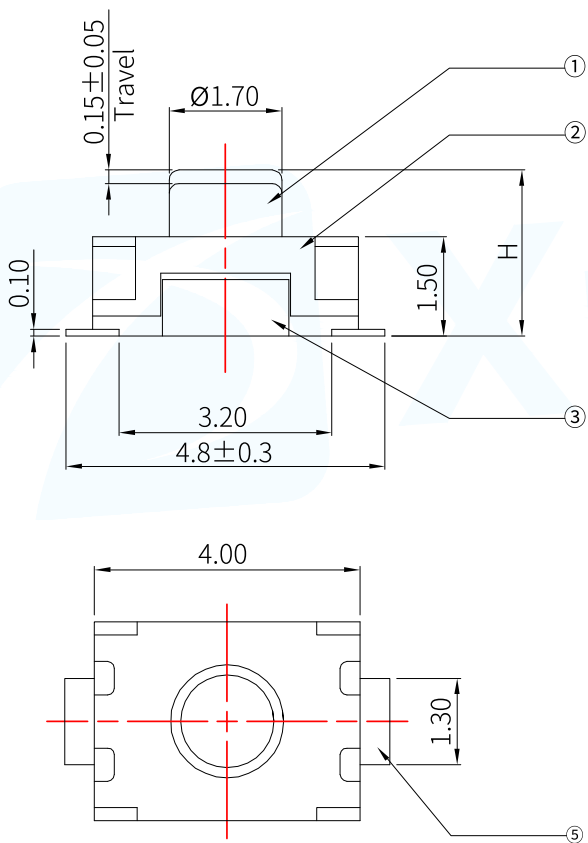
TS-1088
W4.00xD3.00xH

| | |
|---|---|
| 按压力度(Press pressure) : 1.0N/1.6N/2.5N | 开关行程(Switch stroke) : 0.15±0.1mm |
| 操作方式(Operation mode): 正按式/Positive press | 操作寿命(Operation life): 100,000 Cycles Min |
| 储存温度(Storage temperature): -30°C TO +80°C | 焊接温度(Welding temperature): 260±5° 5s |
| 额定负荷(Rated load): DC 12V 50mA | 焊接方式(Welding mode): 贴片式/SMT |
| 接触电阻(Contact resistance): 100mΩ max. | 包装方式(Packaging method): 卷带/Tape & Reel (TR) |
| 绝缘电阻(Insulation resistance): 100MΩ min. | 最小包装(Minimum packing): 3,000/PCS |

外形尺寸 (UNIT:MM) / Size Chart

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更多资料请参考技术选型档!



| PART NO. | |
|-----------------|-----------------|
| TS-1088-ACXXXXX | TS-1088-ARXXXXX |

产品编号/Product No

TS-1088-X X XXX XX

A: 不锈钢(SUS) Operating force
 B: 覆银铜(C5210) Product height
 C: 带柱(Column)
 R: 不带柱(No Column)

产品高度/Product Height

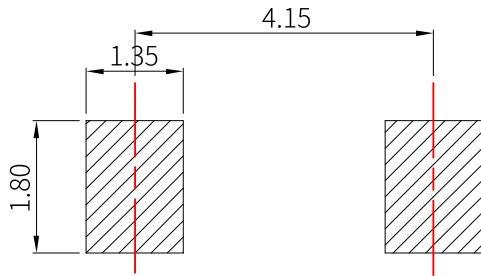
| Code | Product height(mm) | Code | Product height(mm) |
|------|--------------------|------|--------------------|
| 020 | 2.0 | | |
| 025 | 2.5 | | |
| 030 | 3.0 | | |

材质/Material

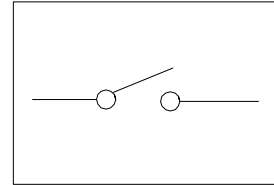
| NO | NAME | MATERIAL | FINISHING |
|----|----------------|----------|---------------------|
| ① | 按钮 Button | LCP | 黑色 Black |
| ② | 盖子 Cover | F.Ag/SUS | 镀镍 Nickel plated |
| ③ | 基座 Base | LCP | 黑色 Black |
| ④ | 弹片 Shrapnel | F.Ag/SUS | 镀银 Silvering |
| ⑤ | 端子 Terminal | Brass | 镀银 Silvering |

操作力度/Operating Force

| Code | Press force(N) | Return force |
|------|----------------|--------------|
| 16 | 1.6 ± 0.5 | 0.4min |
| 26 | 2.6 ± 0.5 | 0.4min |



RECOMMENDED P.C.B LAYOUT
安装尺寸图



CIRCUIT DIAGRAM
回路图

焊接条件 / Welding conditions

● 回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products
温度分布/Temperature distribution



● 手焊式/Hand welding

| 项目/Project | 条件/condition |
|-----------------------------------|--------------|
| 焊接温度 Welding temperature | 350°C max. |
| 持续焊接时间 Continuous welding time | 3s max. |
| 焊剂斗容量 Flux bucket capacity | 60W max. |

● 浸焊式/Immersion soldering

| 项目/Project | 条件/condition |
|------------------------------------|---|
| 助焊剂附着量 Flux adhesion | 不附着于零部件贴装面的程度 Not attached to the mounting surface of components |
| 预热温度 Preheating temperature | 印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max |
| 预热温度时间 Preheat temperature time | 60s max. |
| 焊接温度 welding temperature | 260°C max. |
| 焊接浸渍时间 Welding immersion time | 5s max. |
| 焊接次数 Welding times | 2 times max. |

注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2的CA(K)或CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。